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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Michael D. HAINES

Serial No.: 10/024,724

Filing Date: December 21, 2001

For: METHOD AND APPARATUS FOR INCREASING THE
IMMUNITY OF NEW GENERATION MICROPROCESSORS
FROM ESD EVENTS

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.97 & 1.98

Assistant Commissioner for Patents
Washington, D.C. 20231

February 6, 2002

Sir:

In the matter of the above-identified application, the Examiner's attention is directed to commonly assigned U.S. patent application Serial No. 09/387,048, for Electro-Mechanical Heat Sink Gasket For Shock And Vibration Protection And EMI Suppression On An Exposed Die. The gasket therein has a height greater than an exposed die it is placed over when the gasket is in a non-compressed state. A die reference heat sink is placed over the gasket and exposed die and the gasket is compressed with the die reference heat sink to reduce the height of the gasket until a bottom surface of the heat sink contacts with a top surface of the exposed die. The gasket disclosed therein is made of a non-conductive material including rubber or polyurethane and is at least partially

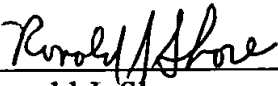
covered by a fine mesh conductive material, including, but not limited to, carbon.

The gasket creates a "faraday cage" around the exposed die to confine EMI emissions therein at the die level.

Assignee's application Serial No. 09/387,048, now allowed, is cited of general interest. The claims in the present application are believed to patentably define over the invention disclosed and claimed therein.

Respectfully submitted,

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